PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/15941
1.3 Title of PCN	ST Crolles (France) STM32H74x & STM32H75x – product enhancements
1.4 Product Category	STM32H742x, STM32H743x, STM32H753x, STM32H750x, STM32H745x, STM32H755x, STM32H747x and STM32H757x
1.5 Issue date	2026-11-06

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	SCHAEFER MARC
2.1.2 Phone	+49 89460062136
2.1.3 Email	marc.schaefer@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	Crolles 300 (France)

4. Description of change		
	Old	New
4.1 Description	Current STM32H74x and STM32H75x products - Crolles 300: revision V Reference Manuals current versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) version 8, Jan 2023 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) version 4, June 2023 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 15 , September 2025 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 6 , September 2025	STM32H74x and STM32H75x products enhancement - Crolles 300: revision T New Reference Manual versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) new version 9, June 2026 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) new version 5, June 2026 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 16 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 7
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change	
5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision visible on top marking is updated : - Crolles 300: revision from "V" to "T"

7. Timing / schedule	
7.1 Date of qualification results	2026-10-15
7.2 Intended start of delivery	2026-12-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15941 MDRF-GPAM RER1401 - PCN15941 - Die 450 CSI Fix Crolles M40- Reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-11-06

9. Attachments (additional documentations)
15941 Public product.pdf 15941 MDRF-GPAM RER1401 - PCN15941 - Die 450 CSI Fix Crolles M40- Reliability plan.pdf 15941 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H743VIT6E	
	STM32H750IBT6	
	STM32H750VBT6TR	
	STM32H743BIT6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

life.augmented

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : ST Crolles (France) STM32H74x & STM32H75x – product enhancements

PCN Reference : EMBEDDED PROCESSING/26/15941

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H742ZGT6	STM32H742IIT6	STM32H753XIH6TR
STM32H747XGH6	STM32H745XGH6	STM32H742XIH6
STM32H755XIH3TR	STM32H742XGH6	STM32H745XIH6TR
STM32H753XIH6	STM32H755XIH3	STM32H755XIH6
STM32H742VGH6	STM32H750XBH6	STM32H745XIH6
STM32H742ZIT6	STM32H743IGK6	STM32H750VBT6TR
STM32H747XIH6	STM32H743VIH6TR	STM32H745XIH3
STM32H750IBK6	STM32H743IIT6	STM32H743XGH6
STM32H742VGT6	STM32H742VIH6	STM32H745IIT3
STM32H757XIH6A	STM32H747AII6	STM32H743VGT6
STM32H745IGK6	STM32H750IBT6	STM32H742IIK6
STM32H743VIT6TR	STM32H757XIH6	STM32H745ZIT6
STM32H747XIH6TR	STM32H753VIT6	STM32H745ZIT3
STM32H745ZGT6	STM32H743VIT6	STM32H743VIH6
STM32H745XIH3TR	STM32H747AGI6	STM32H743IIK6
STM32H753ZIT6	STM32H750ZBT6	STM32H745IIK3
STM32H743ZGT6	STM32H743VGH6	STM32H750VBT6
STM32H753VIH6	STM32H743ZIT6	STM32H742VIT6TR
STM32H743XIH6	STM32H743IIK6TR	STM32H743AII6TR
STM32H742VGT6TR	STM32H755IIT3	STM32H753IIK6
STM32H755XIH6TR	STM32H745IGT6	STM32H742VIT6
STM32H757IIT6	STM32H743AII6	STM32H742AGI6TR
STM32H753IIT6	STM32H743ZIT6TR	STM32H755BIT3
STM32H745BGT6	STM32H747IGT6	STM32H742VIH6TR
STM32H747ZIY6TR	STM32H755IIT6	STM32H742AGI6
STM32H747BIT6	STM32H742IGK6	STM32H755IIK6
STM32H743AGI6	STM32H743IGT6	STM32H745IIK6
STM32H757AII6	STM32H747IIT6	STM32H745IIT6
STM32H755ZIT3	STM32H757BIT6	STM32H742AII6
STM32H743BIT6	STM32H742BGT6	STM32H755ZIT6
STM32H753AII6	STM32H747IIT3	STM32H755IIK3
STM32H757ZIY6TR	STM32H742BIT6	STM32H743BGT6
STM32H753BIT6	STM32H747BGT6	STM32H755BIT6
STM32H745BIT6	STM32H745BIT3	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

life.augmented

PRODUCT/PROCESS CHANGE NOTIFICATION
PCN15941 – Additional information

ST Crolles (France) STM32H74x and STM32H75x – product enhancement

MDRF – General Purpose & Automotive Microcontrollers Division (GPAM)

What are the changes?

Enhancement to secure industrialization for the long-term ensuring the product can be produced and delivered reliably over its full lifecycle using different diffusion sites, while maintaining control of lead time. This PCN applies only to the listed products manufactured in the diffusion fab at ST Crolles.

How can the change be seen?

The standard marking fields example for **UFBGA 10X10 176+25** package

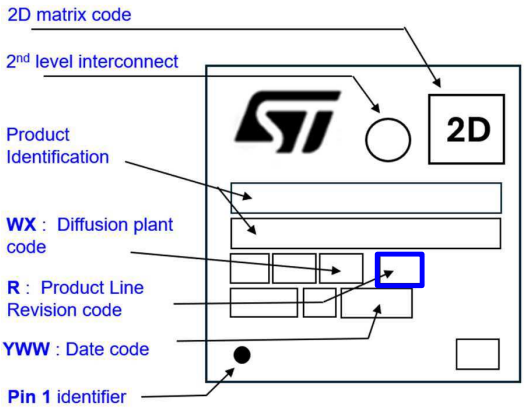
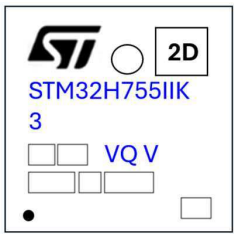
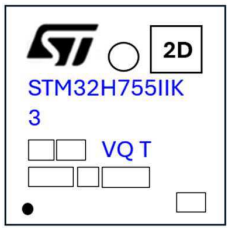


Table_1: marking fields

		ST Crolles 12" (France)	
		old	new
WX	***Diffusion Plant code***	***VQ***	
R	***Revision code***	*V*	***T***

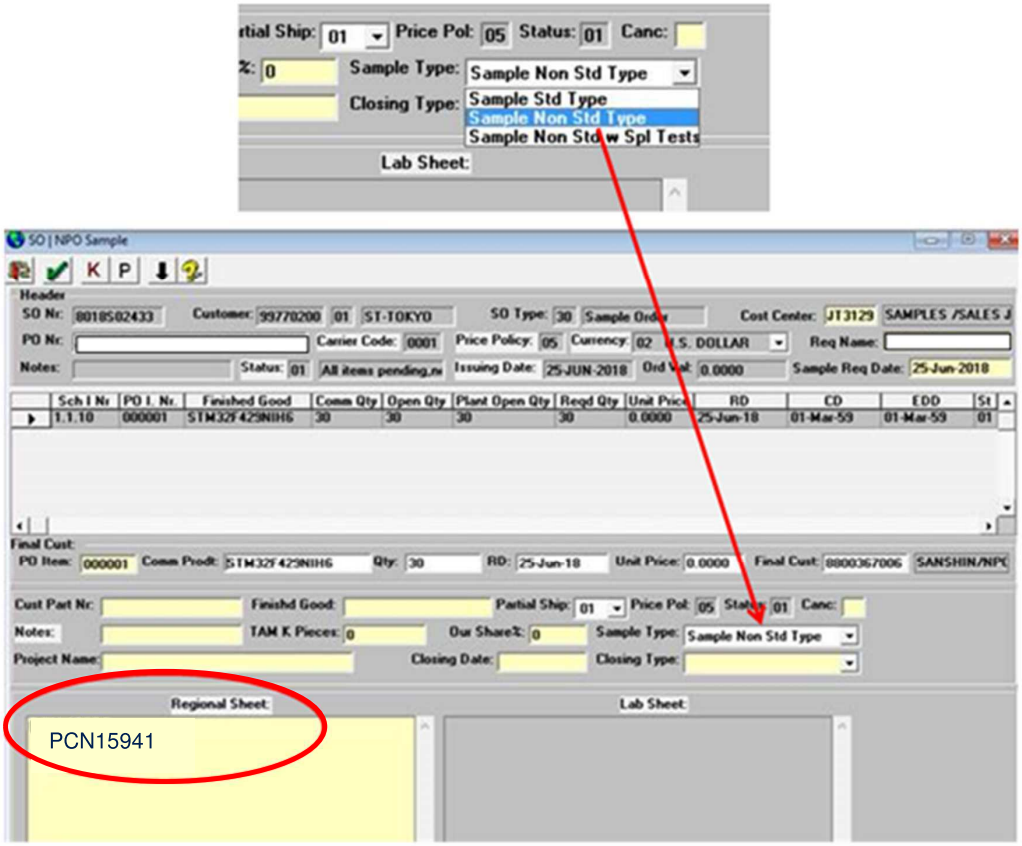
Table_2: Package top view marking examples

	ST Crolles 12" (France)	
Package marking example	old	new
UFBGA 10X10 176+25L (ie: STM32H755IIK3)		

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN15941**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice. This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved



MDRF-GPAM-RER1401 PCN15941
Die 450 – CSI Fix qualification
Crolles M40 – Reliability Plan

June 29th, 2026

GPAM Quality & Reliability Department

MDRF-GPAM-RER1401 – Die 450 Cut 2.3 – Crolles M40

Test	Method	Conditions	Package *	CSI Fix Qual Sample x Lots Acceptance criteria
DIE HTOL	MIL-STD-883 Method 1005 JESD22-A108	125°C & 3.6V 168h	TFBGA240	77 x 1 168h A0/R1
LU	EIA/JESD 78A 0018695 JESD78	125°C	TFBGA240	6 x 1 A0/R1
ESD HBM	ESD Human Body Model JESD22-A114/C101	25°C 1kV, class 1C	TFBGA240	3 x 1 A0/R1
ESD CDM	JEDEC JS-002	Die 450: Voltage = 250V class C1	TFBGA240	3 x 1 A0/R1

Covered by similarity with Die 450 Cut 2.3 – HHGrace reliability – RER2511

life.augmented

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice.
This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved

life.augmented

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16580
1.3 Title of PCN	SAMSUNG Foundry (Korea) STM32H74x & STM32H75x - product enhancements
1.4 Product Category	STM32H742x, STM32H743x, STM32H753x, STM32H750x, STM32H745x, STM32H755x, STM32H747x and STM32H757x
1.5 Issue date	2026-11-09

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	SCHAEFER MARC
2.1.2 Phone	+49 89460062136
2.1.3 Email	marc.schaefer@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like wafer edge region (Polyimide coverage or edge exclusion)	Samsung Foundry (Korea)

4. Description of change		
	Old	New
4.1 Description	Current STM32H74x and STM32H75x products - Samsung Foundry: revision 1 Reference Manuals current versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) version 8, Jan 2023 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) version 4, June 2023 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 15 , September 2025 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 6 , September 2025	STM32H74x and STM32H75x products enhancement - Samsung Foundry: revision 6 New Reference Manual versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) new version 9, June 2026 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) new version 5, June 2026 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 16 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 7
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change	
5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision visible on top marking is updated : - Samsung Foundry : revision from "1" to "6"

7. Timing / schedule	
7.1 Date of qualification results	2026-12-15
7.2 Intended start of delivery	2026-12-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16580 MDRF-GPAM RER2403 - PCN16580 - Die 450 CSI Fix Samsung F M40 - Reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-11-09

9. Attachments (additional documentations)
16580 Public product.pdf 16580 MDRF-GPAM RER2403 - PCN16580 - Die 450 CSI Fix Samsung F M40 - Reliability plan.pdf 16580 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H742IGK6	
	STM32H742IIK6	
	STM32H742VGH6	
	STM32H742VGT6	
	STM32H742VGT6TR	
	STM32H742VIT6	
	STM32H742VIT6TR	
	STM32H742XIH6	
	STM32H742ZGT6	
	STM32H742ZIT6	
	STM32H743AGI6	
	STM32H743AII6	
	STM32H743AII6TR	
	STM32H743IGK6	
	STM32H743IGT6	
	STM32H743IIK6	
	STM32H743IIK6TR	
	STM32H743IIT6	
	STM32H743VGT6	
	STM32H743VGT6TR	
	STM32H743VIH6	
	STM32H743VIH6TR	
	STM32H743VIT6	
	STM32H743VIT6E	
	STM32H743VIT6TR	
	STM32H743XGH6	
	STM32H743XIH6	
	STM32H743XIH6TR	
	STM32H743ZGT6	
	STM32H743ZIT6	
	STM32H743ZIT6TR	
	STM32H745IIK3	
	STM32H745IIK6	
	STM32H745IIK6TR	
	STM32H745IIT3	
	STM32H745IIT6	
	STM32H745XIH3	
	STM32H745XIH6	
	STM32H745ZGT6	

	STM32H745ZIT3	
	STM32H745ZIT6	
	STM32H747AGI6	
	STM32H747AII6	
	STM32H747IIT6	
	STM32H747XGH6	
	STM32H747XIH6	
	STM32H747ZIY6TR	
	STM32H750IBK6	
	STM32H750IBK6TR	
	STM32H750IBT6	
	STM32H750VBT6	
	STM32H750VBT6TR	
	STM32H750XBH6	
	STM32H750XBH6TR	
	STM32H750ZBT6	
	STM32H753AII6	
	STM32H753IIK6	
	STM32H753IIK6TR	
	STM32H753IIT6	
	STM32H753VIH6	
	STM32H753VIT6	
	STM32H753VIT6TR	
	STM32H753XIH6	
	STM32H753XIH6TR	
	STM32H753ZIT6	
	STM32H753ZIT6TR	
	STM32H755IIK3	
	STM32H755IIK6	
	STM32H755IIT6	
	STM32H755XIH3	
	STM32H755XIH6	
	STM32H755ZIT6	
	STM32H757AII6	
	STM32H757IIT6	
	STM32H757XIH6	
	STM32H757XIH6TR	
	STM32H757ZIY6TR	
	STM32H742BGT6	
	STM32H742BIT6	
	STM32H743BGT6	
	STM32H743BIT6	
	STM32H745BIT3	
	STM32H745BIT6	
	STM32H747BIT6	
	STM32H753BIT6	
	STM32H755BIT6	
	STM32H755XIH6TR	
	STM32H757BIT6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

life.augmented

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SAMSUNG Foundry (Korea) STM32H74x & STM32H75x - product enhancements

PCN Reference : EMBEDDED PROCESSING/26/16580

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H742ZGT6	STM32H742IIT6	STM32H753XIH6TR
STM32H747XGH6	STM32H745XGH6	STM32H742XIH6
STM32H755XIH3TR	STM32H742XGH6	STM32H745XIH6TR
STM32H753XIH6	STM32H755XIH3	STM32H755XIH6
STM32H742VGH6	STM32H750XBH6	STM32H745XIH6
STM32H742ZIT6	STM32H743IGK6	STM32H750VBT6TR
STM32H747XIH6	STM32H743VIH6TR	STM32H745XIH3
STM32H750IBK6	STM32H743IIT6	STM32H743XGH6
STM32H742VGT6	STM32H742VIH6	STM32H745IIT3
STM32H757XIH6A	STM32H747AII6	STM32H743VGT6
STM32H745IGK6	STM32H750IBT6	STM32H742IIK6
STM32H743VIT6TR	STM32H757XIH6	STM32H745ZIT6
STM32H747XIH6TR	STM32H753VIT6	STM32H745ZIT3
STM32H745ZGT6	STM32H743VIT6	STM32H743VIH6
STM32H745XIH3TR	STM32H747AGI6	STM32H743IIK6
STM32H753ZIT6	STM32H750ZBT6	STM32H745IIK3
STM32H743ZGT6	STM32H743VGH6	STM32H750VBT6
STM32H753VIH6	STM32H743ZIT6	STM32H742VIT6TR
STM32H743XIH6	STM32H743IIK6TR	STM32H743AII6TR
STM32H742VGT6TR	STM32H755IIT3	STM32H753IIK6
STM32H755XIH6TR	STM32H745IGT6	STM32H742VIT6
STM32H757IIT6	STM32H743AII6	STM32H742AGI6TR
STM32H753IIT6	STM32H743ZIT6TR	STM32H755BIT3
STM32H745BGT6	STM32H747IGT6	STM32H742VIH6TR
STM32H747ZIY6TR	STM32H755IIT6	STM32H742AGI6
STM32H747BIT6	STM32H742IGK6	STM32H755IIK6
STM32H743AGI6	STM32H743IGT6	STM32H745IIK6
STM32H757AII6	STM32H747IIT6	STM32H745IIT6
STM32H755ZIT3	STM32H757BIT6	STM32H742AII6
STM32H743BIT6	STM32H742BGT6	STM32H755ZIT6
STM32H753AII6	STM32H747IIT3	STM32H755IIK3
STM32H757ZIY6TR	STM32H742BIT6	STM32H743BGT6
STM32H753BIT6	STM32H747BGT6	STM32H755BIT6
STM32H745BIT6	STM32H745BIT3	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

life.augmented

PRODUCT/PROCESS CHANGE NOTIFICATION
PCN16580 – Additional information

Samsung Foundry (Korea) STM32H74x and STM32H75x – product enhancement

MDRF – General Purpose & Automotive Microcontrollers Division (GPAM)

What are the changes?

Enhancement to secure industrialization for the long-term ensuring the product can be produced and delivered reliably over its full lifecycle using different diffusion sites, while maintaining control of lead time. This PCN applies only to the listed products manufactured in the diffusion fab at Samsung Foundry.

How can the change be seen?

The standard marking fields example for **UFBGA 10X10 176+25** package

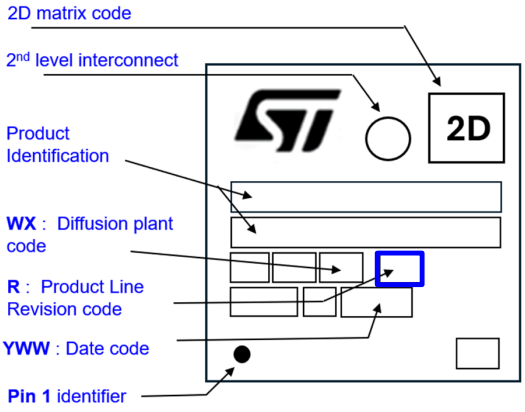
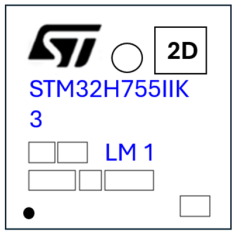
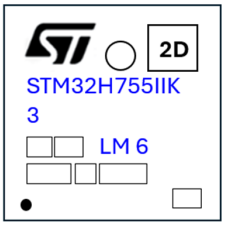


Table_1: marking fields

		SAMSUNG Foundry (South Korea)	
		old	new
WX	***Diffusion Plant code***	***LM***	
R	***Revision code***	*1*	*6*

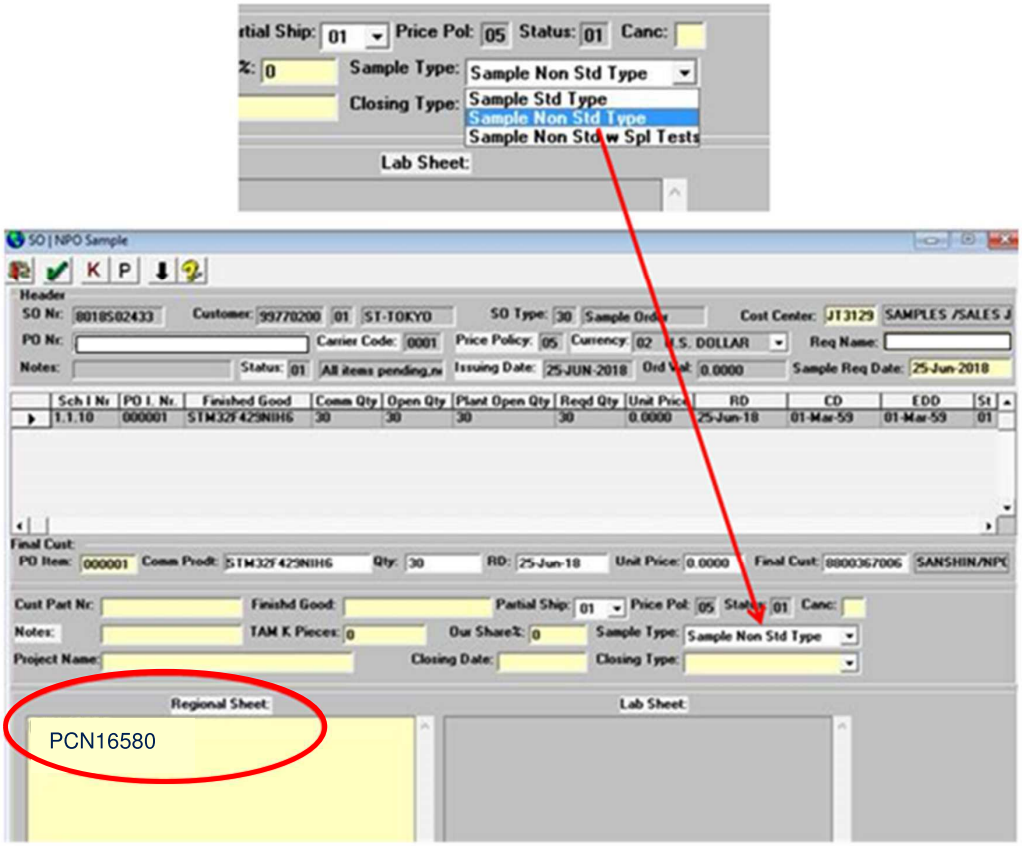
Table_2: Package top view marking examples

	SAMSUNG Foundry (South Korea)	
Package marking example	old	new
UFBGA 10X10 176+25L (ie: STM32H755IIK3)		

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN16580**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice. This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved



MDRF-GPAM-RER2403 PCN16580
Die 450 – CSI Fix qualification
Samsung Foundry (Korea) M40 – Reliability Plan

June 29th, 2026

GPAM Quality & Reliability Department

MDRF-GPAM-RER2403 – Die 450 Cut 2.3 – Samsung Foundry (Korea) M40

Test	Method	Conditions	Package *	CSI Fix Qual Sample x Lots Acceptance criteria
DIE HTOL	MIL-STD-883 Method 1005 JESD22-A108	125°C & 3.6V 168h	TFBGA240	77 x 1 168h A0/R1
LU	EIA/JESD 78A 0018695 JESD78	125°C	TFBGA240	6 x 1 A0/R1
ESD HBM	ESD Human Body Model JESD22-A114/C101	25°C 1kV, class 1C	TFBGA240	3 x 1 A0/R1
ESD CDM	JEDEC JS-002	Die 450: Voltage = 250V class C1	TFBGA240	3 x 1 A0/R1

Covered by similarity with Die 450 Cut 2.3 – HHGrace reliability – RER2511

life.augmented

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice.
This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved

life.augmented

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16579
1.3 Title of PCN	HHGrace (China) STM32H74x & STM32H75x - product enhancements
1.4 Product Category	STM32H742x, STM32H743x, STM32H753x, STM32H750x, STM32H745x, STM32H755x, STM32H747x and STM32H757x
1.5 Issue date	2026-11-06

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	SCHAEFER MARC
2.1.2 Phone	+49 89460062136
2.1.3 Email	marc.schaefer@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design - Die scribe or separation	HHGrace Fab7 and Fab9 (China)

4. Description of change		
	Old	New
4.1 Description	Current STM32H74x and STM32H75x products - HHGrace fab7: revision 2 - HHGrace fab9: revision 3 Reference Manuals current versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) version 8, Jan 2023 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) version 4, June 2023 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 15 , September 2025 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 6 , September 2025	STM32H74x and STM32H75x products enhancement - HHGrace fab7: revision 4 - HHGrace fab9: revision 5 New Reference Manual versions: - RM0433 (STM32H742/743/753 and STM32H750 Single core) new version 9, June 2026 - RM0399 (STM32H745/755 and STM32H747/757 Dual Core) new version 5, June 2026 ErrataSheet - ES0392 (STM32H742/743/753 and STM32H750 Single core) Rev 16 - ES0445 (STM32H745/755 and STM32H747/757 Dual Core) Rev 7
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change	
5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision visible on top marking is updated : - HHGrace fab7: revision from "2" to "4" - HHGrace fab9: revision from "3" to "5"

7. Timing / schedule	
7.1 Date of qualification results	2026-12-15
7.2 Intended start of delivery	2026-12-20

7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16579 MDRF-GPAM RER2511 - PCN16579 - Die 450 CSI Fix HHG M40- Reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-11-06

9. Attachments (additional documentations)
16579 Public product.pdf 16579 MDRF-GPAM RER2511 - PCN16579 - Die 450 CSI Fix HHG M40- Reliability plan.pdf 16579 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H743VIT6E	
	STM32H750IBT6	
	STM32H750VBT6TR	
	STM32H743BIT6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : HHGrace (China) STM32H74x & STM32H75x - product enhancements

PCN Reference : EMBEDDED PROCESSING/26/16579

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H742ZGT6	STM32H742IIT6	STM32H753XIH6TR
STM32H747XGH6	STM32H745XGH6	STM32H742XIH6
STM32H755XIH3TR	STM32H742XGH6	STM32H745XIH6TR
STM32H753XIH6	STM32H755XIH3	STM32H755XIH6
STM32H742VGH6	STM32H750XBH6	STM32H745XIH6
STM32H742ZIT6	STM32H743IGK6	STM32H750VBT6TR
STM32H747XIH6	STM32H743VIH6TR	STM32H745XIH3
STM32H750IBK6	STM32H743IIT6	STM32H743XGH6
STM32H742VGT6	STM32H742VIH6	STM32H745IIT3
STM32H757XIH6A	STM32H747AII6	STM32H743VGT6
STM32H745IGK6	STM32H750IBT6	STM32H742IIK6
STM32H743VIT6TR	STM32H757XIH6	STM32H745ZIT6
STM32H747XIH6TR	STM32H753VIT6	STM32H745ZIT3
STM32H745ZGT6	STM32H743VIT6	STM32H743VIH6
STM32H745XIH3TR	STM32H747AGI6	STM32H743IIK6
STM32H753ZIT6	STM32H750ZBT6	STM32H745IIK3
STM32H743ZGT6	STM32H743VGH6	STM32H750VBT6
STM32H753VIH6	STM32H743ZIT6	STM32H742VIT6TR
STM32H743XIH6	STM32H743IIK6TR	STM32H743AII6TR
STM32H742VGT6TR	STM32H755IIT3	STM32H753IIK6
STM32H755XIH6TR	STM32H745IGT6	STM32H742VIT6
STM32H757IIT6	STM32H743AII6	STM32H742AGI6TR
STM32H753IIT6	STM32H743ZIT6TR	STM32H755BIT3
STM32H745BGT6	STM32H747IGT6	STM32H742VIH6TR
STM32H747ZIY6TR	STM32H755IIT6	STM32H742AGI6
STM32H747BIT6	STM32H742IGK6	STM32H755IIK6
STM32H743AGI6	STM32H743IGT6	STM32H745IIK6
STM32H757AII6	STM32H747IIT6	STM32H745IIT6
STM32H755ZIT3	STM32H757BIT6	STM32H742AII6
STM32H743BIT6	STM32H742BGT6	STM32H755ZIT6
STM32H753AII6	STM32H747IIT3	STM32H755IIK3
STM32H757ZIY6TR	STM32H742BIT6	STM32H743BGT6
STM32H753BIT6	STM32H747BGT6	STM32H755BIT6
STM32H745BIT6	STM32H745BIT3	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved

life.augmented

PRODUCT/PROCESS CHANGE NOTIFICATION
PCN16579 – Additional information

HHGrace WuXi (China) STM32H74x and STM32H75x – product enhancement

MDRF – General Purpose & Automotive Microcontrollers Division (GPAM)

What are the changes?

Enhancement to secure industrialization for the long-term ensuring the product can be produced and delivered reliably over its full lifecycle using different diffusion sites, while maintaining control of lead time. This PCN applies only to the listed products manufactured in the diffusion fab at HHGrace.

How can the change be seen?

The standard marking fields example for **UFBGA 10X10 176+25** package

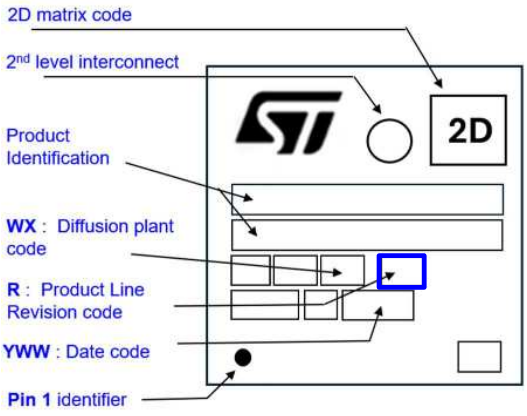
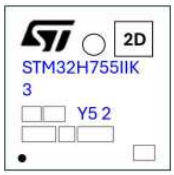
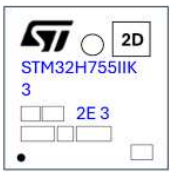
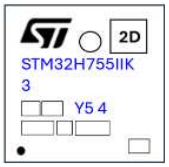
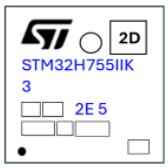


Table_1: marking fields

		HHGrace Wuxi (China)			
		old		new	
		Fab7	Fab9	Fab7	Fab9
WX	***Diffusion Plant code***	**Y5**	**2E**	**Y5**	**2E**
R	***Revision code***	2	3	**4**	**5**

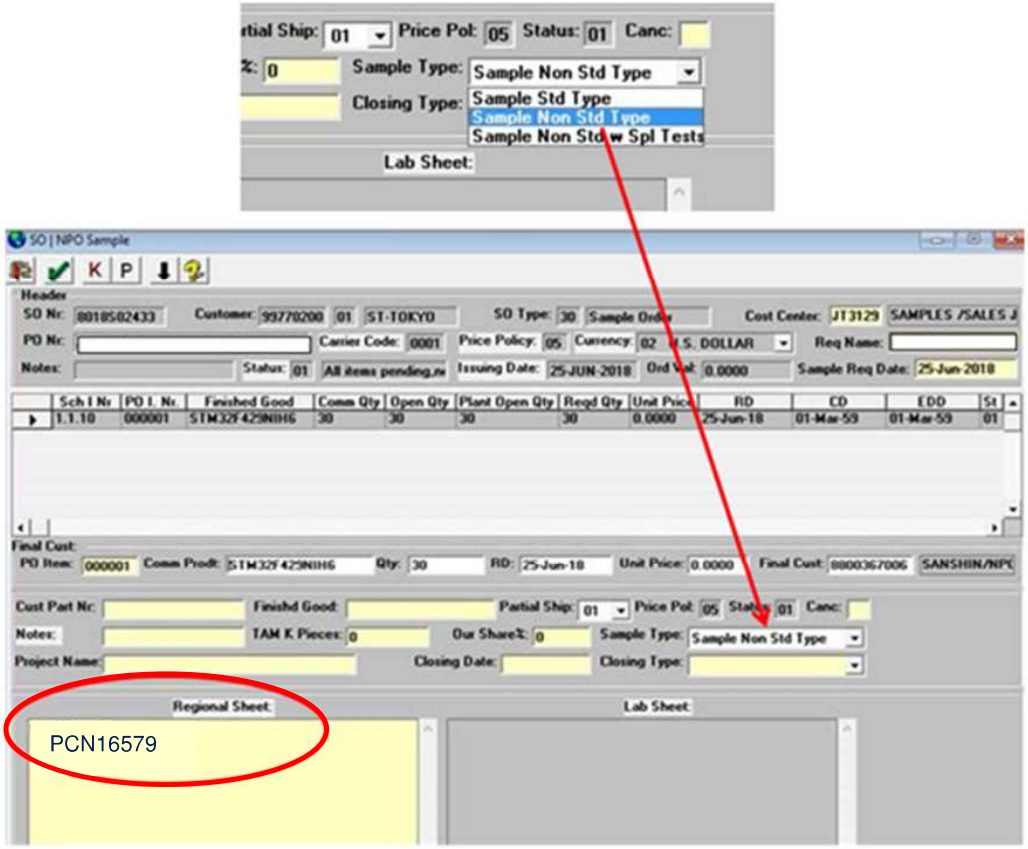
Table_2: Package top view marking examples

	HHGrace Wuxi (China)			
	old		new	
	Fab7	Fab9	Fab7	Fab9
UFBGA 10X10 176+25L (ie: STM32H755IIK3)				

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN16579**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice. This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved



MDRF-GPAM-RER2511 PCN16579
Die 450 – CSI Fix qualification
HHGrace M40 – Reliability Plan

June 29th, 2026

GPAM Quality & Reliability Department

MDRF-GPAM-RER2511 – Die 450 Cut 2.3 – HHGrace M40

Test	Method	Conditions	Package *	CSI Fix Qual Sample x Lots Acceptance criteria
DIE HTOL	MIL-STD-883 Method 1005 JESD22-A108	125°C & 3.6V 168h	TFBGA240	77 x 1 168h A0/R1
LU	EIA/JESD 78A 0018695 JESD78	125°C	TFBGA240	6 x 1 A0/R1
ESD HBM	ESD Human Body Model JESD22-A114/C101	25°C 1kV, class 1C	TFBGA240	3 x 1 A0/R1
ESD CDM	JEDEC JS-002	Die 450: Voltage = 250V class C1	TFBGA240	3 x 1 A0/R1

life.augmented

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice.
This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.
Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.
Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.
ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.

© 2026 STMicroelectronics - All rights reserved

life.augmented